

## 4V Drive Pch MOS FET

## RSQ025P03FRA

## ●Structure

Silicon P-channel MOS FET

## ●Features

- 1) Low On-resistance.(120mΩ at 4.5V)
- 2) High Power Package.(P<sub>D</sub>=1.25W)
- 3) High speed switching.
- 4) Low voltage drive. (4V)

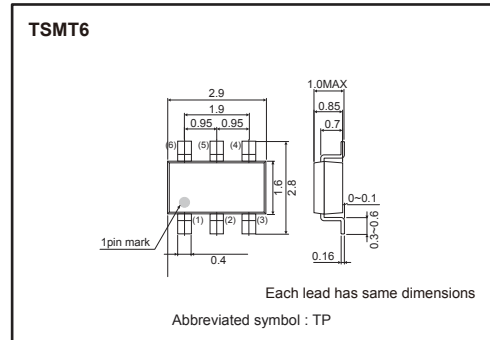
## ●Applications

DC-DC converter

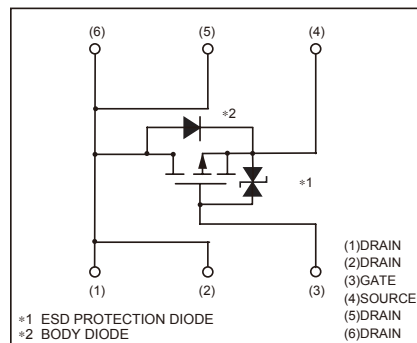
## ●Packaging specifications

Type	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
RSQ025P03FRA		○

## ●External dimensions (Unit : mm)



## ●Equivalent circuit



## ●Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit	
Drain-source voltage	V <sub>DSS</sub>	-30	V	
Gate-source voltage	V <sub>GSS</sub>	±20	V	
Drain current	Continuous	I <sub>D</sub>	±2.5	A
	Pulsed	I <sub>DP</sub> *1	±10	A
Source current (Body diode)	Continuous	I <sub>S</sub>	-1	A
	Pulsed	I <sub>SP</sub> *1	-4	A
Total power dissipation	P <sub>D</sub> *2	1.25	W	
Channel temperature	T <sub>ch</sub>	150	°C	
Range of Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

\*1 P<sub>W</sub>≤10μs, Duty cycle≤1%

\*2 Mounted on a ceramic board

## ●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	R <sub>th(ch-a)</sub> *	100	°C / W

\* Mounted on a ceramic board.

## Transistor

## ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	–	–	±10	μA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	–30	–	–	V	I <sub>D</sub> =–1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	–	–	–1	μA	V <sub>DS</sub> =–30V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS(th)</sub>	–1.0	–	–2.5	V	V <sub>DS</sub> =–10V, I <sub>D</sub> =–1mA
Static drain-source on-state resistance	R <sub>DS(on)</sub> <sup>*</sup>	–	80	110	mΩ	I <sub>D</sub> =–2.5A, V <sub>GS</sub> =–10V
		–	120	165	mΩ	I <sub>D</sub> =–2.5A, V <sub>GS</sub> =–4.5V
		–	145	200	mΩ	I <sub>D</sub> =–1.25A, V <sub>GS</sub> =–4.0V
Forward transfer admittance	Y <sub>fs</sub>   <sup>*</sup>	1.2	–	–	S	V <sub>DS</sub> =–10V, I <sub>D</sub> =–1.25A
Input capacitance	C <sub>iss</sub>	–	320	–	pF	V <sub>DS</sub> =–10V, V <sub>GS</sub> =0V f=1MHz
Output capacitance	C <sub>oss</sub>	–	85	–	pF	
Reverse transfer capacitance	C <sub>rss</sub>	–	60	–	pF	
Turn-on delay time	t <sub>d(on)</sub> <sup>*</sup>	–	8	–	ns	I <sub>D</sub> =–1.25A V <sub>DD</sub> =–15V V <sub>GS</sub> =–10V R <sub>L</sub> =12Ω R <sub>G</sub> =10Ω
Rise time	t <sub>r</sub> <sup>*</sup>	–	11	–	ns	
Turn-off delay time	t <sub>d(off)</sub> <sup>*</sup>	–	33	–	ns	
Fall time	t <sub>f</sub> <sup>*</sup>	–	7	–	ns	
Total gate charge	Q <sub>g</sub>	–	4.4	–	nC	V <sub>DD</sub> =–15V V <sub>GS</sub> =–5V I <sub>D</sub> =–2.5A
Gate-source charge	Q <sub>gs</sub>	–	1.0	–	nC	
Gate-drain charge	Q <sub>gd</sub>	–	1.4	–	nC	

\*PULSED

## ●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub>	–	–	–1.2	V	I <sub>S</sub> =–0.9A, V <sub>GS</sub> =0V

Transistor

●Electrical characteristic curves

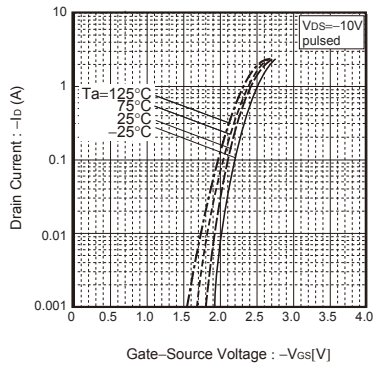


Fig.1 Typical Transfer Characteristics

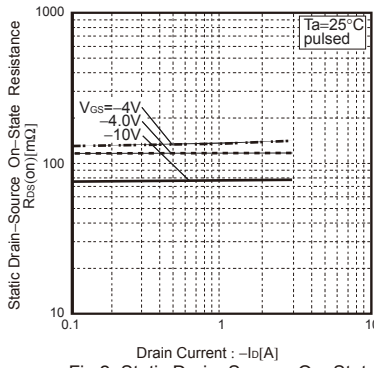


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

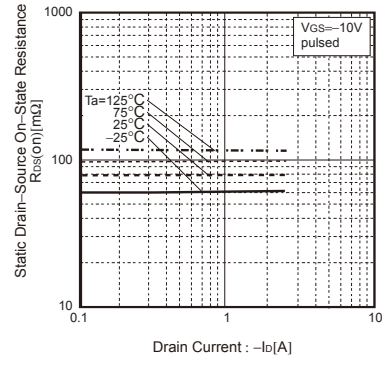


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

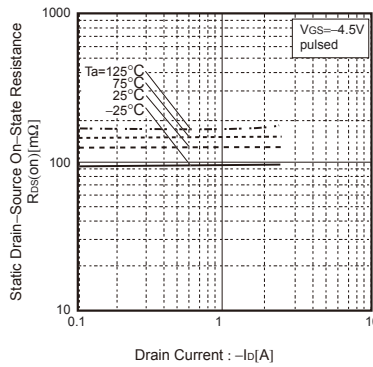


Fig.4 Static Drain-Source On-State Resistance vs. Drain-Current

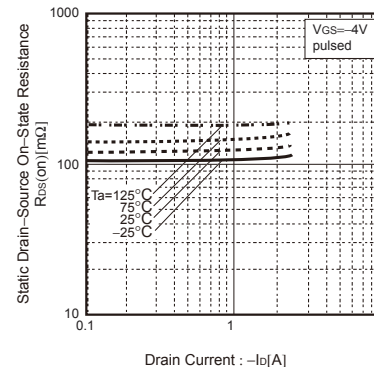


Fig.5 Static Drain-Source On-State Resistance vs. Drain-Current

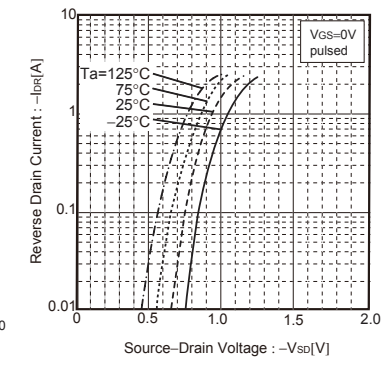


Fig.6 Reverse Drain Current Source-Drain Voltage

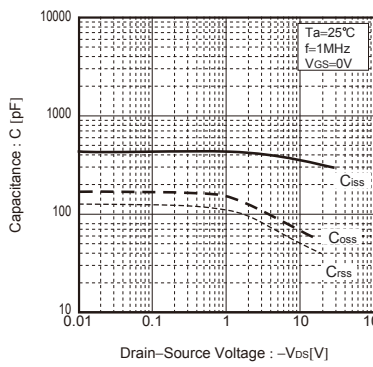


Fig.7 Typical Capacitance vs. Drain-Source Voltage

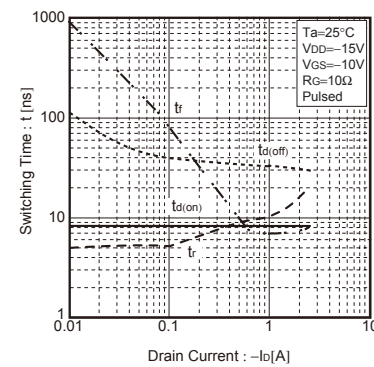


Fig.8 Switching Characteristics

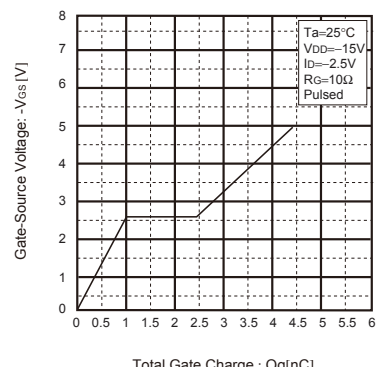


Fig.9 Dynamic Input Characteristics

Transistor

● Measurement circuits

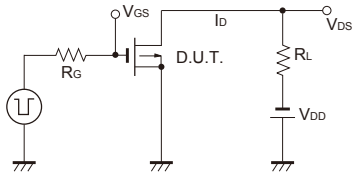


Fig.10 Switching Time Measurement Circuit

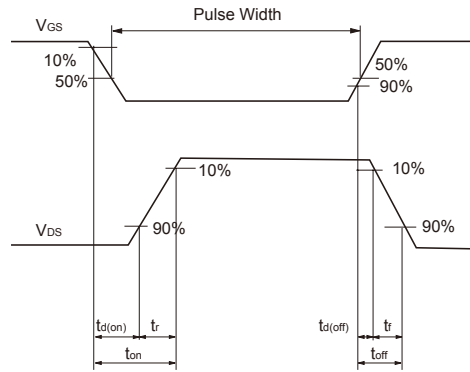


Fig.11 Switching Waveforms

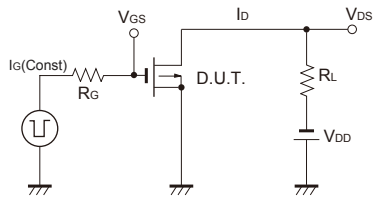


Fig.12 Gate Charge Measurement Circuit

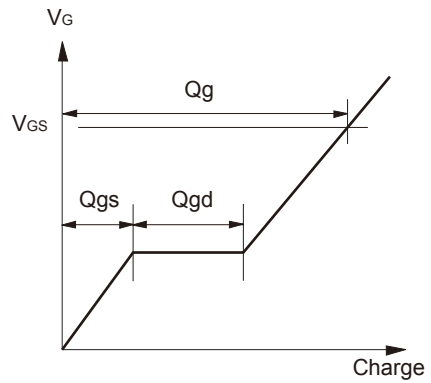


Fig.13 Gate Charge Waveforms

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JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
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  - [h] Use of the Products in places subject to dew condensation
4. The Products are not subject to radiation-proof design.
5. Please verify and confirm characteristics of the final or mounted products in using the Products.
6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
8. Confirm that operation temperature is within the specified range described in the product specification.
9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

**Precautions Regarding Application Examples and External Circuits**

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

**Precaution for Storage / Transportation**

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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